



Discontinuation Notification

202201003DN : Discontinuation Notification with Product Migration for SGTL5000XNAA3/R2 Due to ASECL Punch QFN Line End-of-Service

Note: This notice is NXP Company Proprietary.

Issue Date: Jan 08, 2022 **Effective date:** Jan 09, 2022

PCN Overview

Discontinuation Information

NXP Semiconductors announces the Discontinuation / End-of-Life of the SGTL5000XNAA3 and SGTL5000XNAA3R2 products due to assembly subcontractor ASE Chung-Li Taiwan Punch QFN production line End-of-Service / Decommission, which is effective 31-Mar-2022. New orderable part numbers SGTL5000XNBA3 and SGTL5000XNBA3R2 are offered with Sawn QFN package option for customer supply assurance.

Previously NXP Semiconductors issued Advance PCN 202110016A (22-Oct-2021) and Final PCN 202110016F01 (17-Dec-2021) to ensure customer awareness of the impending Punch QFN non-manufacturable situation, and new Sawn QFN migration part numbers.

Please see the related notifications for details.

This Discontinuation Notice confirms to your company that NXP Semiconductors (NXP) is now discontinuing the manufacture of a number of its integrated circuits and discrete semiconductors listed in the Part Type Affected list included with this notification. In accordance with NXP product discontinuation policy and JEDEC EIA/JESD48, we are hereby giving notice of these product changes so that our customers and partners can adjust their product purchasing records, or make any final lifetime purchases of the discontinued products that can still be supplied by NXP.

While this Discontinuation Notice contains a number of NXP discontinued end-of-life Product Types, the Part Types Affected (PTA) list represents a small percentage of NXP overall semi-conductors product portfolio. Some of these discontinued products have had little to no recent sales history or they are at the end-of-life (EOL) stage. The PTA list may also cover a number of versions or selections of the same basic Product Type.

We regret the inconvenience and impact this notice may cause. NXP Semiconductors' sales, marketing and distribution personnel stand ready to assist you in placing our customers and partners' final orders, or in providing product information you require. On behalf of NXP Semiconductors, we appreciate your understanding and assistance in helping us to help you minimize the impact of this product discontinuation on your company. We look forward to NXP Semiconductors' continued support of your company's semiconductor requirements in the years to come.

Reason for Discontinuance

NXP Semiconductors' assembly subcontractor ASE Chung-Li (ASECL) Taiwan announced the Punch QFN production line End-of-Service / Decommission, which is effective 31-Mar-2022.

Additional information

Additional documents: [view online](#)

Related Notification

Notification	Issue Date	Effective Date	Title
202110016A	Oct 22, 2021		SGTL5000 New Part Numbers with Sawn QFN Conversion Due to ASECL Punch QFN Line End-of-Service
202110016F01	Dec 17, 2021	Mar 17, 2022	SGTL5000 New Part Numbers with Sawn QFN Conversion Due to ASECL Punch QFN Line End-of-Service

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors

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